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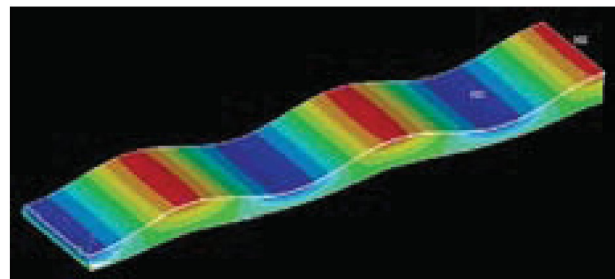
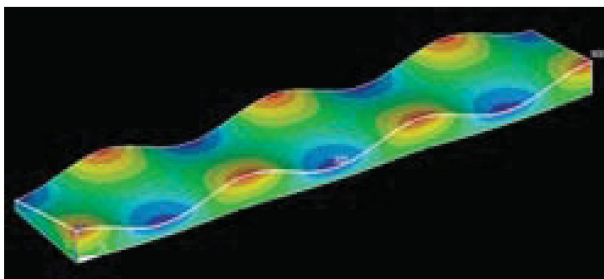
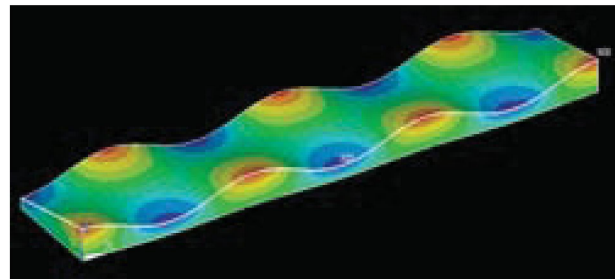
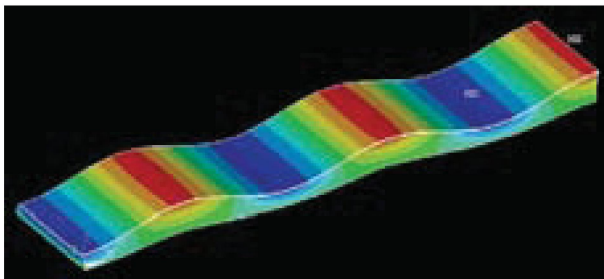
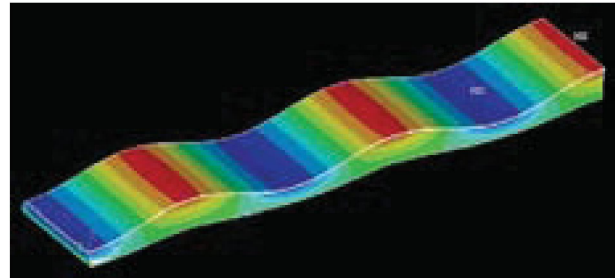
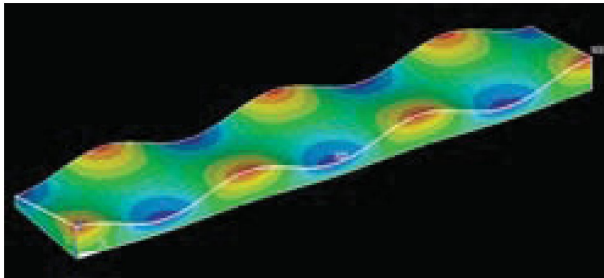
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*For the September 2016 issue, see p. 1293 for Table of Contents.*

*For the October 2016 issue, see p. 1463 for Table of Contents.*

*Cover art from: "Fabrication and Modeling of Nitride Thin-Film Encapsulation Based on Anti-Adhesion-Assisted Transfer Technique and Nitride/BCB Bilayer Wrinkling," by Seonho Seok (pp. 1301–1307, Fig. 3).*



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